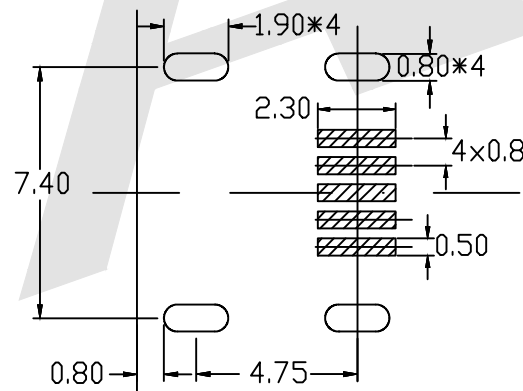
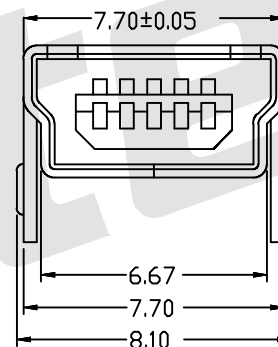
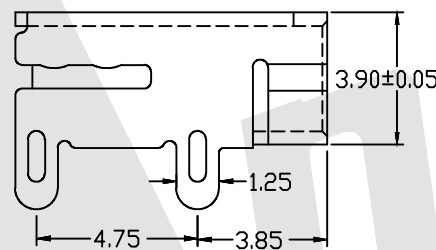
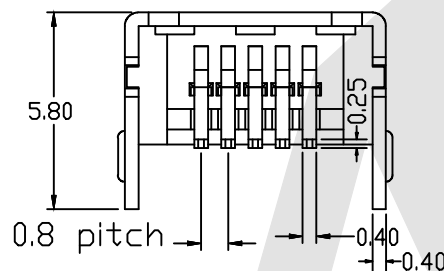
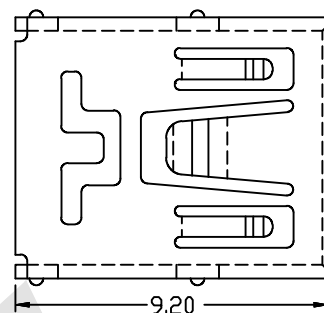


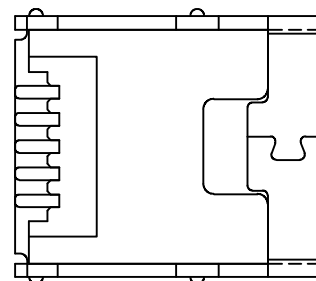
HSF



RoHS



RECOMMENDED PCB LAYOUT



Specifications:

Current Rating: 1A Max

Contact Resistance: 50 milliohms MAX

Dielectric Withstanding Voltage:100V AC AT Sea Level

Insulation Resistance: 500 MEGA ohms MIN

Housing:

Temperature Thermoplastics, LCP UL 94V-0

Contact:

Copper Alloy T=0.25mm Plated Gold in Mating Area;

Tin On Solder Talls

Shell:

Copper Alloy T=0.40mm Nickel/Plating

Ordering Code:

NUFM07 - X - X - X - X - X
① ② ③ ④ ⑤ ⑥

① Series No:

② Shell Material:

B:Brass I:Iron
S:stainless steel

③ Insulator Material:

P:PBT+30%GF
L:LCP

④ Contact Material:

B:Brass P:phosphor copper

⑤ Contact Plating

G0: Gold flash
G1: 3u" Gold
G2: 5u" Gold
G3: 10u" Gold
G4: 15u" Gold
G5: 30u" Gold

⑥ Packing

A:Tray
B:Bag
C:Tube
D:Tape & Reel

Unless Otherwise specified tolerance
X. ±0.35 X.XX: ±0.20
X.X: ±0.25 X.XXX: ±0.15

SCALE: As Shown UNIT: mm
DRAW Lv Xun Hua DATE 11/06/2019
CHECK BobYang DATE 11/06/2019



ANTENK ELECTRONICS CO., LTD
Http://www.antenk.com
E-mail:sales@antenk.com

TITLE: Mini USB 5P Receptacle SMT B
Type(Shell DIP 4Legs)

DRAWING NO: NUFM07-XXXXX

PRODUCT NO: NUFM07-XXXXX

REV	DESCRIPTION	DATE